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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10063915	FILING DATE 05/23/2002	CLASS 228	SUBCLASS 245	GAU 1725	EXAMINER McHenry
**APPLICANTS: Sakai Hiroshi; Suzuki Motoji; Igarashi Makoto; Tanaka Akihiro;					
**CONTINUING DATA VERIFIED: Km					
** FOREIGN APPLICATIONS VERIFIED: Km JAPAN 2001-166910 06/01/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		15574			
Verified and Acknowledged Examiners's initials Km					
TITLE : Solder paste printing method and apparatus for printing solder paste on a board on which wiring patterns are formed					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims
			Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Figs. Drawg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
		Application Examiner	
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